

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A process for forming curable powder, comprising:
  - a) aggregating, in an aqueous dispersion, particles including at least curable resin particles to form aggregated particles;
  - c) coalescing said aggregated particles to form fused particles; and
  - d) removing said fused particles from said aqueous dispersion.
2. (Original) The process of claim 1, said process further comprising mixing said fused particles with at least one curing agent.
3. (Original) The process of claim 1, said curable resin particles comprising at least one curable resin selected from the group consisting of epoxy resins, poly functional epoxy resins, polyester resins, carboxy-functional polyester resins, hydroxy-functional polylester resins, polyol resins, polycarboxylic acid resins, and poly (vinylidene fluoride) resins.
4. (Original) The process of claim 2, said at least one curing agent being selected from the group consisting of polyfunctional amines; dicyanodiamide; bisphenol A; bisphenol S; hydrogenated bisphenol; polyphenolics; imidazoles; betahydroxy-alkylamide; uretdione; and polyfunctional isocyanates.
5. (Original) The process of claim 1, wherein during said aggregating the curable resin particles are aggregated with at least one component selected from the group consisting of colorants, fillers and leveling agents.
6. (Original) The process of claim 5, wherein said colorant is at least one pigment.

7. (Original) A curable powder comprising powder particles formed by the process of claim 1.
8. (Original) The powder of claim 7, wherein said powder further comprises at least one curing agent.
9. (Currently Amended) The powder of claim 7, wherein the powder particles have a volume average diameter of less than or equal to about 30 microns.
10. (Original) A process for forming curable powder, comprising:
  - a) aggregating, in an aqueous dispersion, particles including at least i) curable resin particles and ii) particles comprising at least one curing agent, to form aggregated particles comprising curable resin and curing agent;
  - b) coalescing said aggregated particles to form fused particles; and
  - c) removing said fused particles from said aqueous dispersion.
11. (Original) The process of claim 10, said curable resin particles comprising at least one curable resin selected from the group consisting of epoxy resins, poly functional epoxy resins, polyester resins, carboxy-functional polyester resins, hydroxy-functional polylester resins, polyol resins, polycarboxylic acid resins, and poly (vinylidene fluoride) resins.
12. (Original) The process of claim 10, said at least one curing agent being selected from the group consisting of polyfunctional amines; dicyanodiamide; bisphenol A; bisphenol S; hydrogenated bisphenol; polyphenolics; imidazoles; betahydroxy-alkylamide; uretdione; and polyfunctional isocyanates.
13. (Original) The process of claim 10, wherein during said aggregating the curable resin particles are aggregated with said curing agent and at least one component selected from the group consisting of colorants, fillers and leveling agents.

14. (Original) The process of claim 13, wherein said colorant is at least one pigment.

15. (Original) A curable powder comprising powder particles formed by the process of claim 10.

16. (Currently Amended) The powder of claim 15, wherein the powder particles have a volume average diameter of less than or equal to about 30 microns.

17. (Original) A process for powder coating, comprising:

a) applying a powder according to claim 7 to a conductive surface or to a layer on said conductive surface; and  
b) curing the powder.

18. (Original) The process of claim 17, wherein said conductive surface is a metallic surface.

19. (Original) A process for powder coating, comprising:

a) applying a powder according to claim 15 to a conductive surface or to a layer on said conductive surface;  
b) activating the curing agent to initiate curing the powder; and  
c) allowing the powder to cure.

20. (Original) The process of claim 19, wherein said conductive surface is a metallic surface.

21. (New) The powder of claim 1, comprising at least one curable resin selected from the group consisting of epoxy resins, poly functional epoxy resins, polyester resins, carboxy-functional polyester resins, hydroxy-functional polyester resins, polyol resins, polycarboxylic acid resins, and poly (vinylidene fluoride) resins.

22. (New) The process of claim 10, said curable resin particles comprising at least one curable resin selected from the group consisting of epoxy resins, poly functional epoxy

resins, polyester resins, carboxy-functional polyester resins, hydroxy-functional polyolester resins, polyol resins, polycarboxylic acid resins, and poly (vinylidene fluoride) resins.

23. (New) The powder of claim 15, comprising at least one curable resin selected from the group consisting of epoxy resins, poly functional epoxy resins, polyester resins, carboxy-functional polyester resins, hydroxy-functional polyolester resins, polyol resins, polycarboxylic acid resins, and poly (vinylidene fluoride) resins.

24. (New) A process comprising applying a powder according to claim 7 over a conductive surface; and curing the powder.

25. (New) The process of claim 24, wherein said conductive surface is a metallic surface.

26. (New) The powder of claim 24, comprising at least one curable resin selected from the group consisting of epoxy resins, poly functional epoxy resins, polyester resins, carboxy-functional polyester resins, hydroxy-functional polyolester resins, polyol resins, polycarboxylic acid resins, and poly (vinylidene fluoride) resins.

27. (New) A process comprising applying a powder according to claim 15 over a conductive surface; activating the curing agent to initiate curing the powder; and allowing the powder to cure.

28. (New) The process of claim 27, wherein said conductive surface is a metallic surface.

29. (New) The powder of claim 27, comprising at least one curable resin selected from the group consisting of epoxy resins, poly functional epoxy resins, polyester resins, carboxy-functional polyester resins, hydroxy-functional polyolester resins, polyol resins, polycarboxylic acid resins, and poly (vinylidene fluoride) resins.

30. (New) The process of claim 1, wherein, after removing said fused particles from said aqueous dispersion, said fused particles are dry-blended with at least one additional additive to form said powder.

31. (New) The process of claim 30, wherein the at least one additional additive is selected from the group consisting of surface additives, fluidity assisting additives, flow-promoting agents, flow-control agents, curing agents, fillers, and charge additives.

32. (New) The process of claim 1, wherein the aggregating is accomplished at a temperature below the glass transition temperature of the resin particles.

33. (New) The process of claim 1, wherein the coalescing is accomplished at a temperature above the glass transition temperature of the resin particles.

34. (New) The powder of claim 7, wherein the powder contains resin in an amount of at least about 50 percent by weight.

35. (New) The powder of claim 7, wherein the powder contains colorant in an amount of from about 1 to about 20 percent by weight.

36. (New) The powder of claim 7, wherein the powder has a geometric size distribution of about 1.10 to about 1.25.

37. (New) The powder of claim 7, wherein the particles comprise styrene-acrylate resin.

38. (New) The powder of claim 7, wherein the particles comprise at least one colorant selected from the group consisting of cyan colorants, magenta colorants and yellow colorants.